

R E M A R K S

In the above-identified Office Action the Abstract was objected to, and the claims were all rejected under 35 U.S.C. 112 as being confusing due to their alternative requirements for a ground line and a power supply line, notwithstanding additional requirements were stated for each of such lines. By this response the Abstract has been amended to overcome the objection raised in the Office Action, and the claims have been revised in an attempt to put them in good form with respect to 35 U.S.C. 112. In this regard, it is believed that the Abstract and claims are now in good form. Accordingly, it is respectfully submitted that Claims 9, 12, and 15, which were rejected only on formal grounds, are now unconditionally allowable.

All but Claims 9, 12, and 15 were also rejected as being anticipated by the cited Fang patent. Applicant respectfully requests reconsideration of the allowability of those rejected claims for the reasons given herein.

Applicant's claimed invention includes at least three wiring layers, and requires a basic power supply line formed inside a ground line, both on the same wiring layer. Also, a power supply line, wired to mounting positions of electronic parts via at least one of the wiring layers, is formed inside the basic power supply line when the power supply line and the basic power supply line are projected on one projection plane. This structure enables higher-density wiring as compared with a conventional multi-layered printed wiring board having a ground-only layer and a power supply-only layer.

The Fang patent, on the other hand, relates to a multi-level PCB having a power plane and a ground plane, and a spaced apart signal plane having a patch electrically

isolated from signal traces in the remainder of the signal plane, operatively connected to the power plane or the ground plane (see Col. 1, lines 9-13). The object of the Fang reference is to provide a multi-level printed circuit board containing at least one power plane for conducting and distributing electrical power and at least one ground plane, spaced apart from the power plane, for providing and distributing an electrical ground (Col. 2, lines 14-18). Accordingly, the Fang patent does not suggest Applicant's claimed invention wherein the ground line and the basic power line are formed on the same wiring layer.

For all of these various reasons it is believed that all of the claims are now allowable, wherefore a formal Notice of Allowance is solicited.

Applicant's undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,


Attorney for Applicant

Registration No. 24,613

FITZPATRICK, CELLA, HARPER & SCINTO
30 Rockefeller Plaza
New York, New York 10112-3801
Facsimile: (212) 218-2200